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	Application No.	Applicant(s)	
	10/648,482	JOEI, MASAHIRO	
Notice of Allowability	Examiner	Art Unit	
	Lynne A. Gurley	2812	
The MAILING DATE of this communication at All claims being allowable, PROSECUTION ON THE MERITS herewith (or previously mailed), a Notice of Allowance (PTOL NOTICE OF ALLOWABILITY IS NOT A GRANT OF PATEN of the Office or upon petition by the applicant. See 37 CFR 1	S IS (OR REMAINS) CLOSED in -85) or other appropriate commu T RIGHTS. This application is s .313 and MPEP 1308.	this application. If not includinication will be mailed in due ubject to withdrawal from iss	ded e course. <b>THIS</b>
1. $igotimes$ This communication is responsive to $the$ interview sum	mary of 4/28/04 and Attorney's a	approval given 5/10/04.	
2. ⊠ The allowed claim(s) is/are <u>1-10</u> .			
3. $igotimes$ The drawings filed on $27$ August 2003 are accepted by	the Examiner.		
4.  Acknowledgment is made of a claim for foreign priorit  a)  All b)  Some* c)  None of the:  1.  Certified copies of the priority documents it  2.  Certified copies of the priority documents it  3.  Copies of the certified copies of the priority	nave been received.  nave been received in Application of documents have been received.  TE" of this communication to file DNMENT of this application.  ubmitted. Note the attached EXA gives reason(s) why the oath or must be submitted.  person's Patent Drawing Review.	n No  I in this national stage application this national stage application are reply complying with the result.  MINER'S AMENDMENT or leader a declaration is deficient.	equirements
(b) ☐ including changes required by the attached Exami Paper No./Mail Date Identifying indicia such as the application number (see 37 Cleach sheet. Replacement sheet(s) should be labeled as such	FR 1.84(c)) should be written on th	e drawings in the front (not th	e back) of
7. ☐ DEPOSIT OF and/or INFORMATION about the deattached Examiner's comment regarding REQUIREME	eposit of BIOLOGICAL MATE	RIAL must be submitted.	Note the
Attachment(s)  1. ☑ Notice of References Cited (PTO-892)  2. ☐ Notice of Draftperson's Patent Drawing Review (PTO-94)  3. ☐ Information Disclosure Statements (PTO-1449 or PTO/8	48) 6. ⊠ Interview Su Paper No./	formal Patent Application (PT ummary (PTO-413), Mail Date <u>5/10/04</u> . Amendment/Comment	<sup>-</sup> O-152)
Paper No./Mail Date 4. ☐ Examiner's Comment Regarding Requirement for Depo of Biological Material	sit 8. ⊠ Examiner's 9. □ Other	Statement of Reasons for All	owance
	ı	CYNNE A. GURLEY (	1

U.S. Patent and Trademark Office PTOL-37 (Rev. 1-04) TC 2800, AU 2812

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## **EXAMINER'S AMENDMENT**

1. An examiner's amendment to the record appears below. Should the changes and/or additions be unacceptable to applicant, an amendment may be filed as provided by 37 CFR 1.312. To ensure consideration of such an amendment, it MUST be submitted no later than the payment of the issue fee.

Authorization for this examiner's amendment was given in a telephone interview with Ramyar M. Farid on 5/10/04.

The application has been amended as follows:

## In the Claims:

1. (Currently amended) A method for fabricating a semiconductor device comprising the steps of:

forming an insulating film on a conductive pattern formed on a substrate; forming a resist pattern on the insulating film;

performing etching to the insulating film using the resist pattern as a mask to form in the insulating film an opening at which part of a surface of the conductive pattern is exposed;

forming, by performing oxygen plasma treatment, a passive antioxidant layer on the part of the surface of the conductive pattern exposed while removing the resist pattern; and

depositing a conductive film on the conductive pattern from which the antioxidant layer has been removed,

wherein the antioxidant layer contains CuO as a main component.

- 2. (Currently amended) The method of claim 1, wherein the conductive pattern contains Cu and the antioxidant layer contains CuO as a main component.
- 3. (Previously presented) The method of claim 2, wherein the step of forming an antioxidant layer includes performing oxygen plasma treatment with a substrate temperature of 120°C or less.
- 4. (Original) The method of claim 2, wherein the step of forming an antioxidant layer includes performing oxygen plasma treatment with a chamber pressure of 40 Pa or less.

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5. (Currently amended) A method for fabricating a semiconductor device comprising the steps

of:

forming an insulating film on a conductive pattern formed on a substrate;

forming a resist pattern on the insulating film;

performing etching to the insulating film using the resist pattern as a mask to form in the insulating film an opening at which part of the surface of the conductive pattern is exposed;

forming, by performing oxygen plasma treatment, a passive antioxidant layer on the part of the surface of the conductive pattern exposed;

after forming the antioxidant layer, removing the resist pattern by performing oxygen plasma treatment; and

depositing a conductive film on the conductive pattern from which the antioxidant layer has been removed.

wherein the antioxidant layer contains CuO as a main component.

- 6. (Currently amended) The method of claim 5, wherein the conductive pattern contains Cu and the antioxidant layer contains CuO as a main component.
- 7. (Previously presented) The method of claim 6, wherein the step of removing the resist pattern includes performing oxygen plasma treatment with a substrate temperature of not less than 200°C and not more than 250°C.

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8. (Original) The method of claim 5, wherein the step of forming an antioxidant layer includes performing oxygen plasma treatment with a first substrate temperature, and

the step of removing the resist pattern includes performing oxygen plasma treatment with a second substrate temperature which is higher than the first substrate temperature.

9. (Original) The method of claim 5, wherein the step of forming an antioxidant layer includes performing oxygen plasma treatment at a first pressure, and

the step of removing the resist pattern includes performing oxygen plasma treatment at a second pressure which is higher than the first pressure.

10. (Previously presented) The method of claim 5, wherein the step of forming the antioxidant layer includes performing reactive ion treatment to the conductive pattern.

## Reasons For Allowance

2. The following is an examiner's statement of reasons for allowance: The closest prior art of record fails to teach or to suggest, that "the antioxidant layer contains CuO as a main component".

Any comments considered necessary by applicant must be submitted no later than the payment of the issue fee and, to avoid processing delays, should preferably accompany the issue fee. Such submissions should be clearly labeled "Comments on Statement of Reasons for Allowance."

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Any inquiry concerning this communication or earlier communications from the examiner should be directed to Lynne A. Gurley whose telephone number is 571-272-1670. The examiner can normally be reached on M-F 7:30-4:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, John Niebling can be reached on 571-272-1679. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Lynne A. Gurley

Primary Patent Examiner

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TC 2800, AU 2812

LAG May 10, 2004